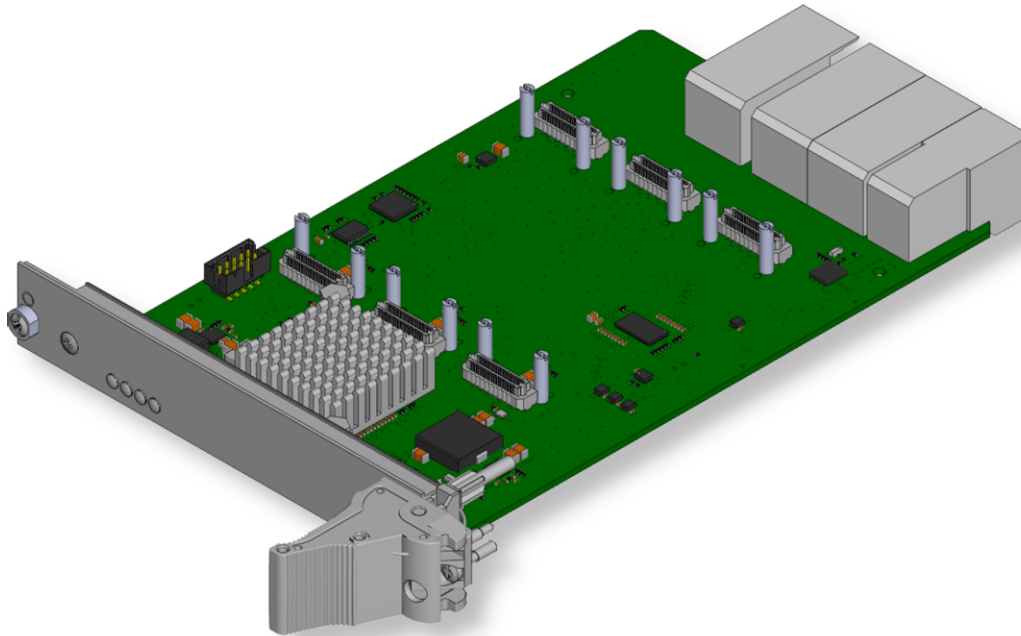


TCPS210 CompactPCI-Serial Carrier with 3 QMC Sites, PCIe Gen3 x4, Rear-I/O



TCPS210-10R

Application Information

The TCPS210 is a PICMG CPCI-S.0 R3.0 compatible 3U module providing 3 single-width QMC sites, used to build modular, flexible and cost effective I/O solutions for all kinds of applications like process control, medical systems, telecommunication and traffic control.

It can be populated with up to 3 single-width QMC modules, a double-width QMC module and a single-width QMC module, or a triple-width QMC module.

The PCI Express x4 link from the host board (CompactPCI-Serial CPU) is distributed to the 3 QMC sites as x4 links by a non-blocking PCI-Express switch.

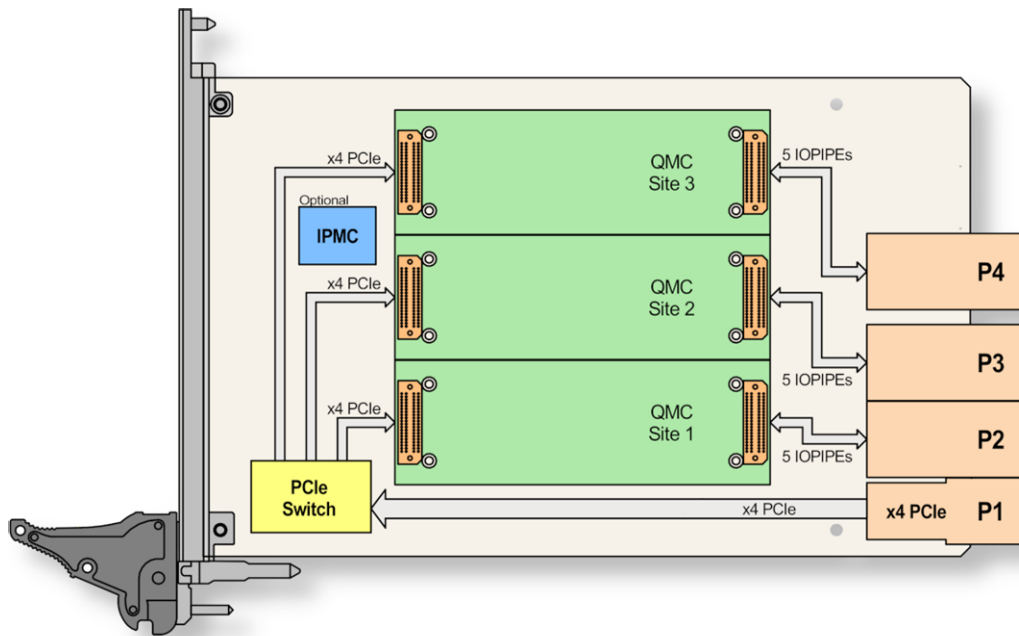
QMC I/O is accessible via the CompactPCI-Serial Rear-I/O connectors P2, P3 and P4.

For enhanced system monitoring an IPMC controller is mounted on the TCPS210, enabling real-time QMC health status tracking and seamless communication. For integration in your specific system configuration please contact TEWS.

The TCPS210 QMC Carrier is designed to support integration into conduction cooled systems. Please contact TEWS to discuss your specific system requirements.

Technical Information

- Form Factor: 3U CPCI-S.0 R3.0
 - Board size: 160 mm x 100 mm
- PCI Express (Base Specification 3.1) compliant Gen3 x4 host interface
- Management controller (optional)
 - QMC health status monitoring
 - CPCI-S.0 system management bus
- 3 single-width QMC sites
 - PCIe Gen3 x4
 - Rear-I/O
- Operating temperature -40 °C to +85 °C
- MTBF (MIL-HDBK217F/FN2 GB 20 °C)
 - 321 000 h



TCPS210

Order Information

RoHS Compliant

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For a conduction cooled variant please contact TEWS.

For the availability of non-RoHS compliant (lead solder) products please contact TEWS.